

S/N 09/733,289

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Xiao-Chun Mu et al.	Examiner:	DiLinh Nguyen
Serial No.:	09/733,289	Group Art Unit:	2814
Filed:	December 8, 2000	Docket:	884.798US1
Customer No.:	45457	Confirmation No.:	2980
Title:	Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers		

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

The attached documents were discovered as a result of a Search Report in Applicants' corresponding foreign patent application. Enclosed for the Examiner's information is a copy of the cited documents and the Search Report.

Pursuant to 37 C.F.R. §1.97(c)(1) and 37 C.F.R. §1.97(e)(1), Applicants state that each item of information contained in the Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement. As a final action has been mailed, the Commissioner is hereby authorized to charge Deposit Account No. 19-0743 \$180.00 in order to have this Supplemental Information Disclosure Statement considered.

Applicant brings to the attention of the Examiner the following Office Actions and responses associated with one or both of the inventors of the instant application and/or the assignee of the instant application. This material is available and accessible at the United States Patent and Trademark Office.

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MICROELECTRONIC SUBSTRATES WITH INTEGRATED DEVICES

Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Advisory Action mailed 9/8/2004, 3 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Response filed 8/13/2004 Final Office Action mailed 4/13/2004, 17 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Final Office Action mailed 4/13/2004, 10 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Final Office Action mailed 8/22/2003, 10 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Response filed 12/22/2003 Final Office Action mailed 8/22/2003, 28 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Response filed 7/23/2002 Restriction Requirement mailed 7/15/2002, 1 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Response filed 9/20/2002 Restriction Requirement mailed 9/10/2002, 1 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Response filed 1/14/2003 Restriction Requirement mailed 12/17/2002, 1 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Response filed 3/5/2003 Restriction Requirement mailed 2/14/2003, 1 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Response filed 6/13/2003 Restriction Requirement mailed 5/20/2003, 1 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Restriction Requirement mailed 7/15/2002, 4 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Restriction Requirement mailed 9/10/2002, 4 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Restriction Requirement mailed 12/17/2002, 5 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Restriction Requirement mailed 2/14/2003, 5 pgs
Application Serial No. 09/884,595, (Atty Ref 884.D51US1) Restriction Requirement mailed 5/20/2003, 5 pgs

MICROELECTRONIC SUBSTRATES WITH INTEGRATED DEVICES

Application Serial No. 10/964,238, (Atty Ref 884.D51US2) Notice of Allowance mailed 2/13/2006, 2 pgs
Application Serial No. 10/964,238, (Atty Ref 884.D51US2) Response filed 5/2/2005 Restriction Requirement mailed 4/1/2005, 16 pgs
Application Serial No. 10/964,238, (Atty Ref 884.D51US2) Response filed 8/29/2005 Restriction Requirement mailed 7/27/2005, 1 pgs
Application Serial No. 10/964,238, (Atty Ref 884.D51US2) Restriction Requirement mailed 4/1/2005, 4 pgs
Application Serial No. 10/964,238, (Atty Ref 884.D51US2) Restriction Requirement mailed 7/27/2005, 5 pgs

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Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications, and Non-Published Applications identifiable by USPTO Serial Number, are no longer required to be provided to the Office. Notification of this change to this effect was provided in the United States Patent and Trademark Office OG Notice dated October 19, 2004. Thus, Applicant has not included copies of any US Patents or US Patent Applications identifiable by serial number that may be cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

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Date 2-25-08

By



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JNG:jld

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: MS ~~Amendment~~, ~~Commissioner~~ for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 25th day of February, 2008.

JUDY DENT

Name


Signature